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#### General Information

|             |   |
|-------------|---|
| Series      | KONNEKT Comm U2J                          |
| Style       | KONNEKT                                   |
| Description | SMD, MLCC, KONNEKT, Ultra-Stable, Class I |
| Features    | High Density Packaging                    |
| RoHS        | Yes                                       |
| Termination | Tin                                       |
| AEC-Q200    | No  |
| Chip Size   | 1812-3                                    |
| Shelf Life  | 78 Weeks                                  |
| MSL         | 1   |

#### Dimensions

|   |                 |
|---|-----------------|
| L | 4.5mm +/-0.3mm  |
| W | 5.3mm +/-0.6mm  |
| T | 3.2mm +/-0.3mm  |
| B | 0.6mm +/-0.35mm |

#### Packaging Specifications

|                    |                          |
|--------------------|--------------------------|
| Packaging          | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 500                      |

#### Specifications

|                                 |                       |
|---------------------------------|-----------------------|
| Capacitance                     | 1.4 uF                |
| Tolerance                       | 5%                    |
| Voltage DC                      | 50 VDC                |
| Dielectric Withstanding Voltage | 125 VDC               |
| Temperature Range               | -55/+125°C            |
| Temp. Coefficient               | U2J                   |
| Dissipation Factor              | 0.1% 1 kHz 25C        |
| Aging Rate                      | 0.1% Loss/Decade Hour |
| Insulation Resistance           | 714.29 MOhms          |

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